TOSHIBA DIODE SILICON EPITAXIAL SCHOTTKY BARRIER TYPE

1 S S 3 4 4

ULTRA HIGH SPEED SWITCHING APPLICATION.

Low Forward Voltage $: V_{F(3)} = 0.50V \text{ (Typ.)}$

Fast Reverse Recovery Time : $t_{rr} = 20$ ns (Typ.)

High Average Forward Current: IO=0.5A (Max.)

MAXIMUM RATINGS (Ta = 25°C)

CHARACTERISTIC	SYMBOL	RATING	UNIT
Maximum (Peak) Reverse Voltage	v_{RM}	25	V
Reverse Voltage	$V_{\mathbf{R}}$	20	V
Maximum (Peak) Forward Current	I_{FM}	1500	mA
Average Forward Current	IO	500	mA
Surge Current (10ms)	I_{FSM}	5	A
Power Dissipation	P	200	mW
Junction Temperature	T_{j}	125	°C
Storage Temperature	$\mathrm{T_{stg}}$	-55~125	°C
Operating Temperature	${ m T_{opr}}$	-40~100	$^{\circ}\mathrm{C}$

Unit in mm

1. ANODE 2. N.C.

JEDEC TO-236MOD **EIAJ** SC-59

3. CATHODE

TOSHIBA 1-3G1B

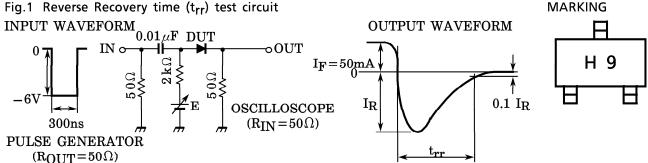
Weight: 0.012g

S-MINI

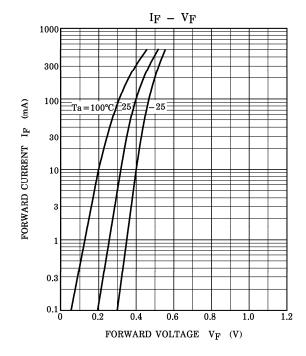
ELECTRICAL CHARACTERISTICS (Ta = 25°C)

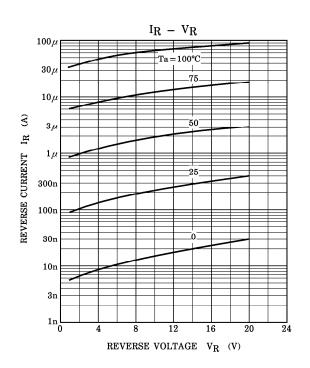
CHARACTERISTIC	SYMBOL	TEST CONDITION	MIN.	TYP.	MAX.	UNIT
Forward Voltage	$V_{F(1)}$	I _F =10mA	_	0.30	_	V
	$V_{F(2)}$	$I_{ m F}$ = 100mA	_	0.38	_	
	$V_{F(3)}$	$I_{ m F}$ = 500mA	_	0.50	0.55	
Reverse Current	$I_{R(1)}$	$V_R = 10V$	_	_	20	μ A
	$I_{R(2)}$	$V_R = 20V$	_	_	100	
Total Capacitance	C_{T}	$V_R=0$, f=1MHz	_	120		рF
Reverse Recovery Time	t _{rr}	I _F =50mA (Fig.1)	_	20	_	ns

Fig.1 Reverse Recovery time (t_{rr}) test circuit



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